

IN THE CLAIMS

Kindly amend the claims as follows:

1. (Original) An image sensor module for use with a camera apparatus,
the image sensor module comprising:
 - a circuit board section including a transparent material and having an upper surface onto which a circuit pattern and an infrared ray filter are simultaneously bonded;
 - an image sensor chip bonded to a lower surface of the circuit board section using a flip chip bonding technique;
 - a lens holder bonded to the upper surface of the circuit board section using an epoxy bonding process; and
 - a lens assembly bonded to an upper surface of the lens holder using the epoxy bonding process.
2. (Original) The image sensor module as claimed in claim 1, wherein the circuit board section includes a printed circuit board and a flexible circuit board.
3. (Original) The image sensor module as claimed in claim 1, wherein transparent material includes CU PET or CU PI.
4. (Original) A terminal comprising:
 - a camera lens module having an image sensor module, the image sensor including,
 - a circuit board section including transparent material and having an

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upper surface onto which a circuit pattern and an infrared ray filter are simultaneously bonded;

an image sensor chip bonded to a lower surface of the circuit board section through a flip chip bonding technique;

a lens holder bonded to the upper surface of the circuit board section through an epoxy bonding process; and

a lens assembly bonded to an upper surface of the lens holder through the epoxy bonding process.

5. (Original) The terminal as claimed in claim 4, wherein the terminal is a video camera, an electronic still camera, a PC camera terminal, or a PDA.

6. (Original) A method for assembling an image sensor module of a camera apparatus, the method comprising the steps of:

i) simultaneously bonding a circuit pattern and an infrared ray filter to an upper surface of a circuit board section;

ii) bonding an image sensor chip to a lower surface of the circuit board section using a flip chip bonding technique;

iii) bonding a lens holder to the upper surface of the circuit board section using an epoxy bonding process; and

iv) bonding a lens assembly to an upper surface of the lens holder using the epoxy bonding process.

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7. (Original) The method as claimed in claim 6, wherein, in step i), a bonding part including transparent material is formed on the circuit board section in order to bond the circuit pattern and the infrared ray filter to the circuit section.